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ne datasneet namber will be changing.		
Device Family	Change From:	Change To:
TLIN1029-Q1	SLLSEY5B	SLLSEY5C
TLIN2029-Q1	SLLSEY6B	SLLSEY6C

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TLIN1029-Q1

http://www.ti.com/product/TLIN2029-Q1

# **Reason for Change:**

To accurately reflect device characteristics.

## Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

# Changes to product identification resulting from this PCN:

None.

### **Product Affected:**

TLIN1029DQ1	TLIN1029DRBRQ1	TLIN1029DRBTQ1	TLIN1029DRQ1
TLIN1029MDRBRQ1	TLIN2029DQ1	TLIN2029DRBRQ1	TLIN2029DRBTQ1
TLIN2029DRQ1			

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